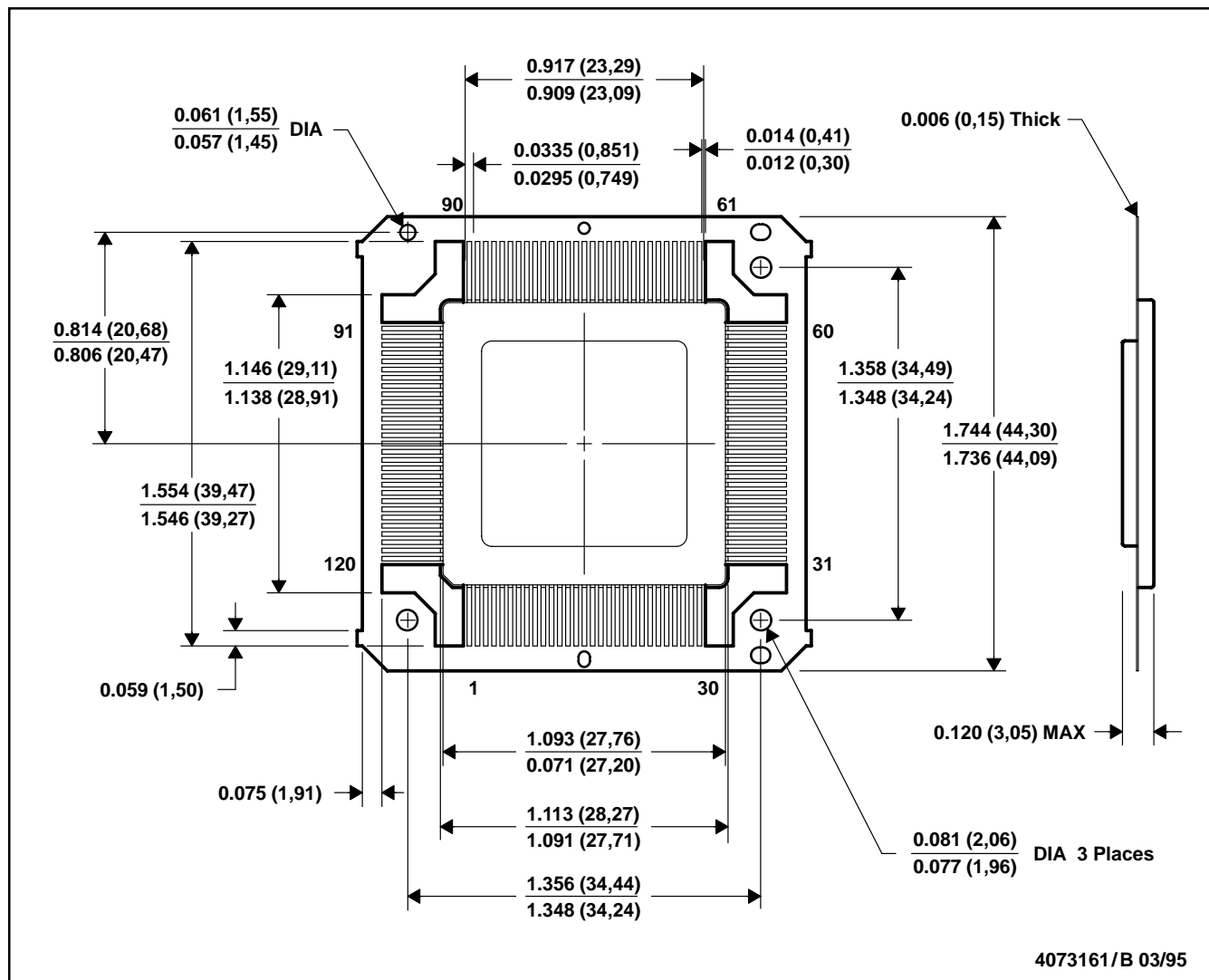


HBG (S-CQFP-F120)

CERAMIC FLATPACK WITH TIE-BAR CARRIER



- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

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